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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	832
Number of Logic Elements/Cells	8320
Total RAM Bits	106496
Number of I/O	136
Number of Gates	526000
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep20k200eqc208-3">https://www.e-xfl.com/product-detail/intel/ep20k200eqc208-3</a>

## Functional Description

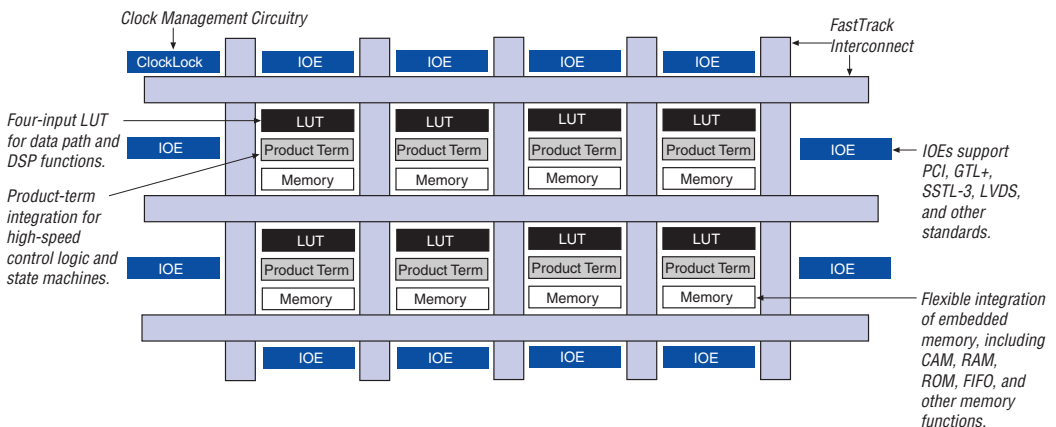
APEX 20K devices incorporate LUT-based logic, product-term-based logic, and memory into one device. Signal interconnections within APEX 20K devices (as well as to and from device pins) are provided by the FastTrack<sup>®</sup> Interconnect—a series of fast, continuous row and column channels that run the entire length and width of the device.

Each I/O pin is fed by an I/O element (IOE) located at the end of each row and column of the FastTrack Interconnect. Each IOE contains a bidirectional I/O buffer and a register that can be used as either an input or output register to feed input, output, or bidirectional signals. When used with a dedicated clock pin, these registers provide exceptional performance. IOEs provide a variety of features, such as 3.3-V, 64-bit, 66-MHz PCI compliance; JTAG BST support; slew-rate control; and tri-state buffers. APEX 20KE devices offer enhanced I/O support, including support for 1.8-V I/O, 2.5-V I/O, LVCMOS, LVTTL, LVPECL, 3.3-V PCI, PCI-X, LVDS, GTL+, SSTL-2, SSTL-3, HSTL, CTT, and 3.3-V AGP I/O standards.

The ESB can implement a variety of memory functions, including CAM, RAM, dual-port RAM, ROM, and FIFO functions. Embedding the memory directly into the die improves performance and reduces die area compared to distributed-RAM implementations. Moreover, the abundance of cascadable ESBs ensures that the APEX 20K device can implement multiple wide memory blocks for high-density designs. The ESB's high speed ensures it can implement small memory blocks without any speed penalty. The abundance of ESBs ensures that designers can create as many different-sized memory blocks as the system requires.

Figure 1 shows an overview of the APEX 20K device.

**Figure 1. APEX 20K Device Block Diagram**



Each LE has two outputs that drive the local, MegaLAB, or FastTrack Interconnect routing structure. Each output can be driven independently by the LUT's or register's output. For example, the LUT can drive one output while the register drives the other output. This feature, called register packing, improves device utilization because the register and the LUT can be used for unrelated functions. The LE can also drive out registered and unregistered versions of the LUT output.

The APEX 20K architecture provides two types of dedicated high-speed data paths that connect adjacent LEs without using local interconnect paths: carry chains and cascade chains. A carry chain supports high-speed arithmetic functions such as counters and adders, while a cascade chain implements wide-input functions such as equality comparators with minimum delay. Carry and cascade chains connect LEs 1 through 10 in an LAB and all LABs in the same MegaLAB structure.

### *Carry Chain*

The carry chain provides a very fast carry-forward function between LEs. The carry-in signal from a lower-order bit drives forward into the higher-order bit via the carry chain, and feeds into both the LUT and the next portion of the carry chain. This feature allows the APEX 20K architecture to implement high-speed counters, adders, and comparators of arbitrary width. Carry chain logic can be created automatically by the Quartus II software Compiler during design processing, or manually by the designer during design entry. Parameterized functions such as library of parameterized modules (LPM) and DesignWare functions automatically take advantage of carry chains for the appropriate functions.

The Quartus II software Compiler creates carry chains longer than ten LEs by linking LABs together automatically. For enhanced fitting, a long carry chain skips alternate LABs in a MegaLAB™ structure. A carry chain longer than one LAB skips either from an even-numbered LAB to the next even-numbered LAB, or from an odd-numbered LAB to the next odd-numbered LAB. For example, the last LE of the first LAB in the upper-left MegaLAB structure carries to the first LE of the third LAB in the MegaLAB structure.

Figure 6 shows how an  $n$ -bit full adder can be implemented in  $n + 1$  LEs with the carry chain. One portion of the LUT generates the sum of two bits using the input signals and the carry-in signal; the sum is routed to the output of the LE. The register can be bypassed for simple adders or used for accumulator functions. Another portion of the LUT and the carry chain logic generates the carry-out signal, which is routed directly to the carry-in signal of the next-higher-order bit. The final carry-out signal is routed to an LE, where it is driven onto the local, MegaLAB, or FastTrack Interconnect routing structures.

The counter mode uses two three-input LUTs: one generates the counter data, and the other generates the fast carry bit. A 2-to-1 multiplexer provides synchronous loading, and another AND gate provides synchronous clearing. If the cascade function is used by an LE in counter mode, the synchronous clear or load overrides any signal carried on the cascade chain. The synchronous clear overrides the synchronous load. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

### *Clear & Preset Logic Control*

Logic for the register's clear and preset signals is controlled by LAB-wide signals. The LE directly supports an asynchronous clear function. The Quartus II software Compiler can use a NOT-gate push-back technique to emulate an asynchronous preset. Moreover, the Quartus II software Compiler can use a programmable NOT-gate push-back technique to emulate simultaneous preset and clear or asynchronous load. However, this technique uses three additional LEs per register. All emulation is performed automatically when the design is compiled. Registers that emulate simultaneous preset and load will enter an unknown state upon power-up or when the chip-wide reset is asserted.

In addition to the two clear and preset modes, APEX 20K devices provide a chip-wide reset pin (DEV\_CLRn) that resets all registers in the device. Use of this pin is controlled through an option in the Quartus II software that is set before compilation. The chip-wide reset overrides all other control signals. Registers using an asynchronous preset are preset when the chip-wide reset is asserted; this effect results from the inversion technique used to implement the asynchronous preset.

## **FastTrack Interconnect**

In the APEX 20K architecture, connections between LEs, ESBs, and I/O pins are provided by the FastTrack Interconnect. The FastTrack Interconnect is a series of continuous horizontal and vertical routing channels that traverse the device. This global routing structure provides predictable performance, even in complex designs. In contrast, the segmented routing in FPGAs requires switch matrices to connect a variable number of routing paths, increasing the delays between logic resources and reducing performance.

The FastTrack Interconnect consists of row and column interconnect channels that span the entire device. The row interconnect routes signals throughout a row of MegaLAB structures; the column interconnect routes signals throughout a column of MegaLAB structures. When using the row and column interconnect, an LE, IOE, or ESB can drive any other LE, IOE, or ESB in a device. See [Figure 9](#).

**Table 9. APEX 20K Routing Scheme**

Source	Destination								
	Row I/O Pin	Column I/O Pin	LE	ESB	Local Interconnect	MegaLAB Interconnect	Row FastTrack Interconnect	Column FastTrack Interconnect	FastRow Interconnect
Row I/O Pin					✓	✓	✓	✓	
Column I/O Pin								✓	✓ (1)
LE					✓	✓	✓	✓	
ESB					✓	✓	✓	✓	
Local Interconnect	✓	✓	✓	✓					
MegaLAB Interconnect					✓				
Row FastTrack Interconnect						✓		✓	
Column FastTrack Interconnect						✓	✓		
FastRow Interconnect					✓ (1)				

**Note to Table 9:**

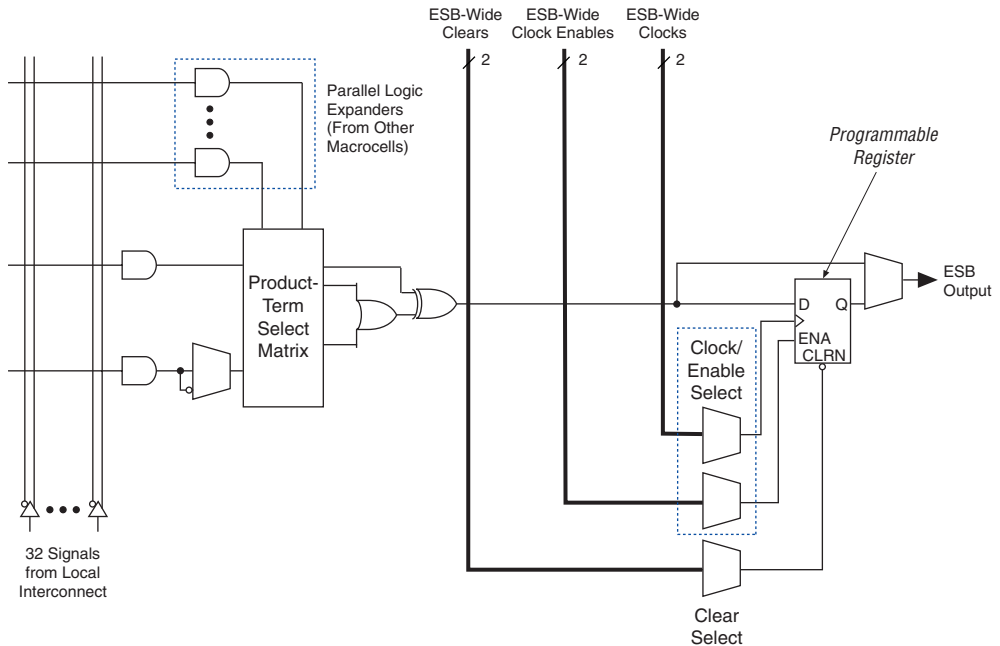
(1) This connection is supported in APEX 20KE devices only.

## Product-Term Logic

The product-term portion of the MultiCore architecture is implemented with the ESB. The ESB can be configured to act as a block of macrocells on an ESB-by-ESB basis. Each ESB is fed by 32 inputs from the adjacent local interconnect; therefore, it can be driven by the MegaLAB interconnect or the adjacent LAB. Also, nine ESB macrocells feed back into the ESB through the local interconnect for higher performance. Dedicated clock pins, global signals, and additional inputs from the local interconnect drive the ESB control signals.

In product-term mode, each ESB contains 16 macrocells. Each macrocell consists of two product terms and a programmable register. [Figure 13](#) shows the ESB in product-term mode.

**Figure 14. APEX 20K Macrocell**



For registered functions, each macrocell register can be programmed individually to implement D, T, JK, or SR operation with programmable clock control. The register can be bypassed for combinatorial operation. During design entry, the designer specifies the desired register type; the Quartus II software then selects the most efficient register operation for each registered function to optimize resource utilization. The Quartus II software or other synthesis tools can also select the most efficient register operation automatically when synthesizing HDL designs.

Each programmable register can be clocked by one of two ESB-wide clocks. The ESB-wide clocks can be generated from device dedicated clock pins, global signals, or local interconnect. Each clock also has an associated clock enable, generated from the local interconnect. The clock and clock enable signals are related for a particular ESB; any macrocell using a clock also uses the associated clock enable.

If both the rising and falling edges of a clock are used in an ESB, both ESB-wide clock signals are used.

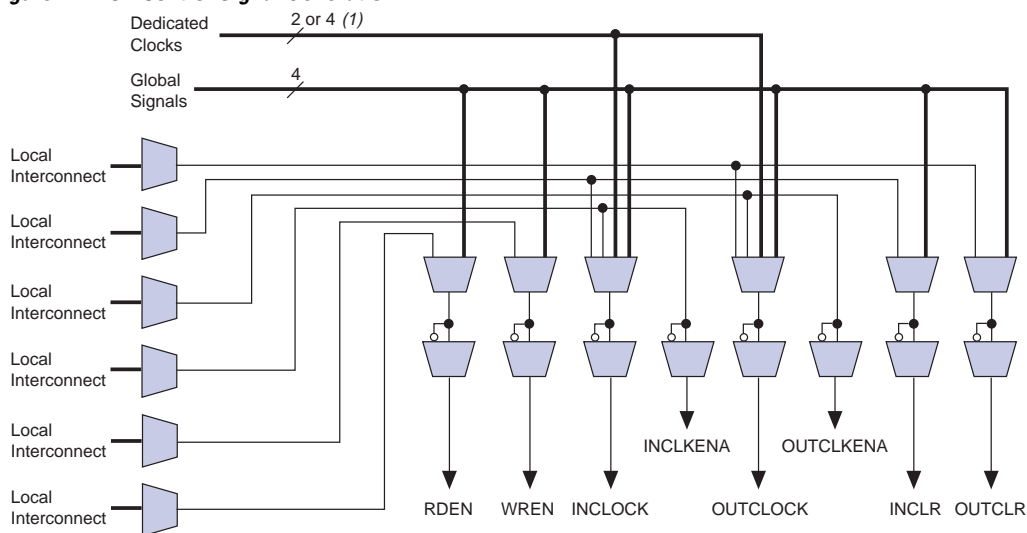


For more information on APEX 20KE devices and CAM, see *Application Note 119 (Implementing High-Speed Search Applications with APEX CAM)*.

## Driving Signals to the ESB

ESBs provide flexible options for driving control signals. Different clocks can be used for the ESB inputs and outputs. Registers can be inserted independently on the data input, data output, read address, write address, WE, and RE signals. The global signals and the local interconnect can drive the WE and RE signals. The global signals, dedicated clock pins, and local interconnect can drive the ESB clock signals. Because the LEs drive the local interconnect, the LEs can control the WE and RE signals and the ESB clock, clock enable, and asynchronous clear signals. [Figure 24](#) shows the ESB control signal generation logic.

**Figure 24. ESB Control Signal Generation**



**Note to Figure 24:**

(1) APEX 20KE devices have four dedicated clocks.

An ESB is fed by the local interconnect, which is driven by adjacent LEs (for high-speed connection to the ESB) or the MegaLAB interconnect. The ESB can drive the local, MegaLAB, or FastTrack Interconnect routing structure to drive LEs and IOEs in the same MegaLAB structure or anywhere in the device.

## Implementing Logic in ROM

In addition to implementing logic with product terms, the ESB can implement logic functions when it is programmed with a read-only pattern during configuration, creating a large LUT. With LUTs, combinatorial functions are implemented by looking up the results, rather than by computing them. This implementation of combinatorial functions can be faster than using algorithms implemented in general logic, a performance advantage that is further enhanced by the fast access times of ESBs. The large capacity of ESBs enables designers to implement complex functions in one logic level without the routing delays associated with linked LEs or distributed RAM blocks. Parameterized functions such as LPM functions can take advantage of the ESB automatically. Further, the Quartus II software can implement portions of a design with ESBs where appropriate.

## Programmable Speed/Power Control

APEX 20K ESBs offer a high-speed mode that supports very fast operation on an ESB-by-ESB basis. When high speed is not required, this feature can be turned off to reduce the ESB's power dissipation by up to 50%. ESBs that run at low power incur a nominal timing delay adder. This Turbo Bit™ option is available for ESBs that implement product-term logic or memory functions. An ESB that is not used will be powered down so that it does not consume DC current.

Designers can program each ESB in the APEX 20K device for either high-speed or low-power operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths operate at reduced power.

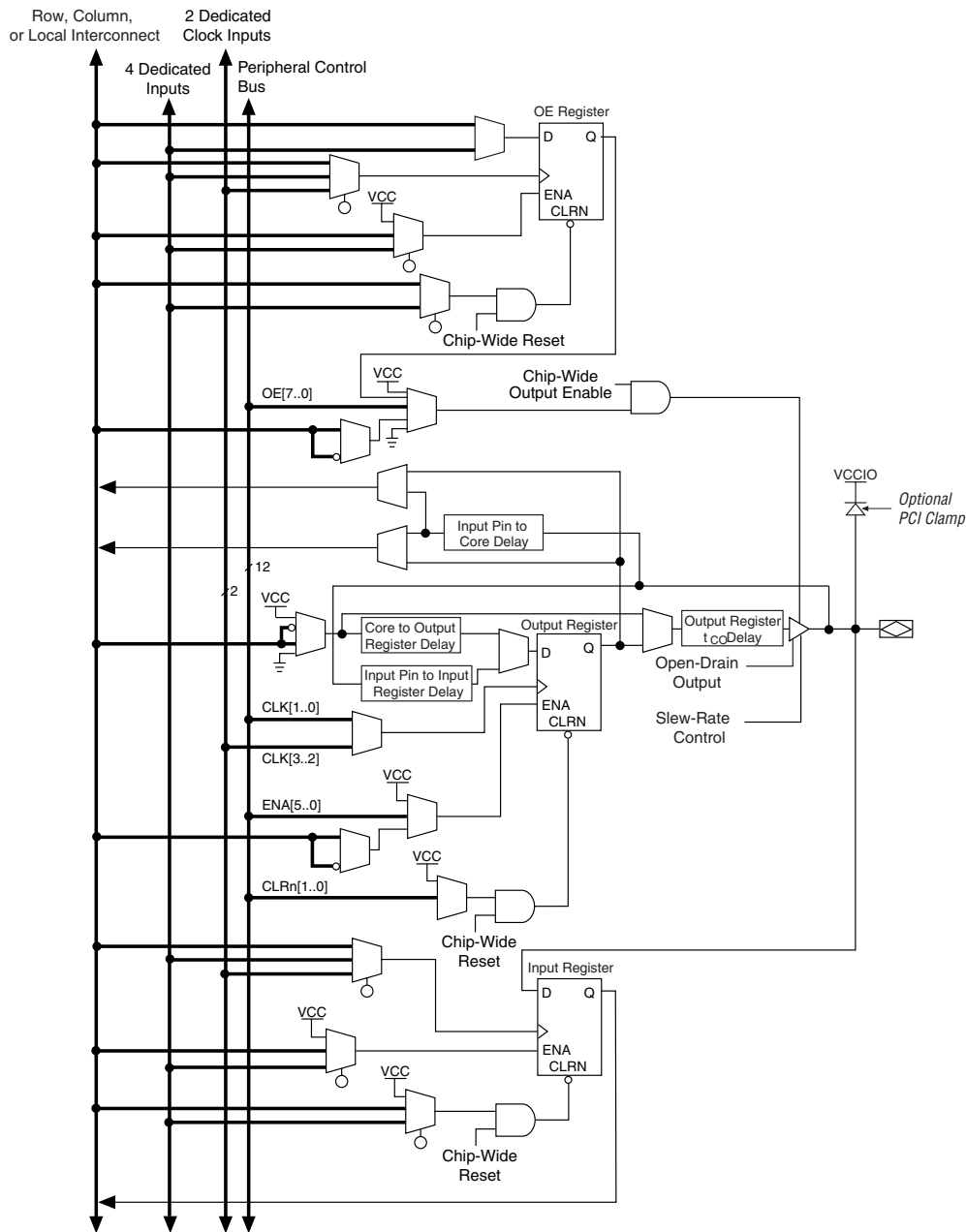
## I/O Structure

The APEX 20K IOE contains a bidirectional I/O buffer and a register that can be used either as an input register for external data requiring fast setup times, or as an output register for data requiring fast clock-to-output performance. IOEs can be used as input, output, or bidirectional pins. For fast bidirectional I/O timing, LE registers using local routing can improve setup times and OE timing. The Quartus II software Compiler uses the programmable inversion option to invert signals from the row and column interconnect automatically where appropriate. Because the APEX 20K IOE offers one output enable per pin, the Quartus II software Compiler can emulate open-drain operation efficiently.

The APEX 20K IOE includes programmable delays that can be activated to ensure zero hold times, minimum clock-to-output times, input IOE register-to-core register transfers, or core-to-output IOE register transfers. A path in which a pin directly drives a register may require the delay to ensure zero hold time, whereas a path in which a pin drives a register through combinatorial logic may not require the delay.



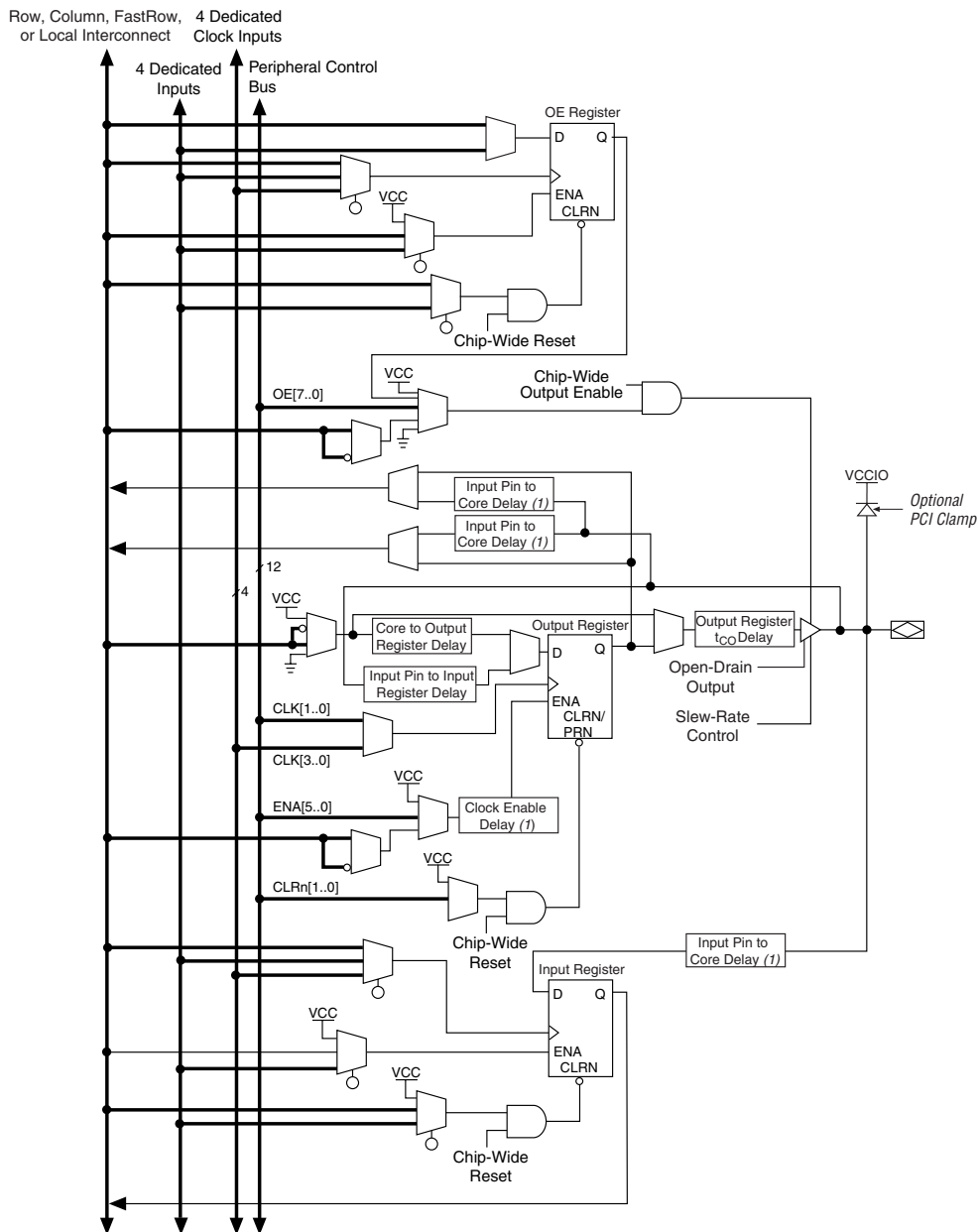
**Figure 25. APEX 20K Bidirectional I/O Registers** *Note (1)*



**Note to Figure 25:**

(1) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

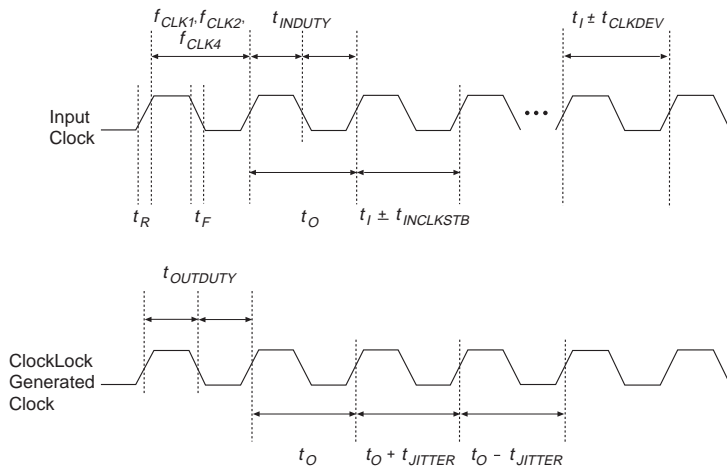
**Figure 26. APEX 20KE Bidirectional I/O Registers** Notes (1), (2)



**Notes to Figure 26:**

- (1) This programmable delay has four settings: off and three levels of delay.
- (2) The output enable and input registers are LE registers in the LAB adjacent to the bidirectional pin.

**Figure 30. Specifications for the Incoming & Generated Clocks** *Note (1)*



**Note to Figure 30:**

- (1) The  $t_I$  parameter refers to the nominal input clock period; the  $t_O$  parameter refers to the nominal output clock period.

Table 15 summarizes the APEX 20K ClockLock and ClockBoost parameters for -1 speed-grade devices.

<b>Table 15. APEX 20K ClockLock &amp; ClockBoost Parameters for -1 Speed-Grade Devices (Part 1 of 2)</b>				
<b>Symbol</b>	<b>Parameter</b>	<b>Min</b>	<b>Max</b>	<b>Unit</b>
$f_{OUT}$	Output frequency	25	180	MHz
$f_{CLK1}$ (1)	Input clock frequency (ClockBoost clock multiplication factor equals 1)	25	180 (1)	MHz
$f_{CLK2}$	Input clock frequency (ClockBoost clock multiplication factor equals 2)	16	90	MHz
$f_{CLK4}$	Input clock frequency (ClockBoost clock multiplication factor equals 4)	10	48	MHz
$t_{OUTDUTY}$	Duty cycle for ClockLock/ClockBoost-generated clock	40	60	%
$f_{CLKDEV}$	Input deviation from user specification in the Quartus II software (ClockBoost clock multiplication factor equals 1) (2)		25,000 (3)	PPM
$t_R$	Input rise time		5	ns
$t_F$	Input fall time		5	ns
$t_{LOCK}$	Time required for ClockLock/ClockBoost to acquire lock (4)		10	$\mu$ s

The APEX 20K device instruction register length is 10 bits. The APEX 20K device USERCODE register length is 32 bits. [Tables 20 and 21](#) show the boundary-scan register length and device IDCODE information for APEX 20K devices.

**Table 20. APEX 20K Boundary-Scan Register Length**

Device	Boundary-Scan Register Length
EP20K30E	420
EP20K60E	624
EP20K100	786
EP20K100E	774
EP20K160E	984
EP20K200	1,176
EP20K200E	1,164
EP20K300E	1,266
EP20K400	1,536
EP20K400E	1,506
EP20K600E	1,806
EP20K1000E	2,190
EP20K1500E	1 <a href="#">(1)</a>

**Note to [Table 20](#):**

- (1) This device does not support JTAG boundary scan testing.



For DC Operating Specifications on APEX 20KE I/O standards, please refer to *Application Note 117 (Using Selectable I/O Standards in Altera Devices)*.

**Table 30. APEX 20KE Device Capacitance** Note (15)

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input capacitance	$V_{IN} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		8	pF
$C_{INCLK}$	Input capacitance on dedicated clock pin	$V_{IN} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		12	pF
$C_{OUT}$	Output capacitance	$V_{OUT} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		8	pF

**Notes to Tables 27 through 30:**

- (1) See the *Operating Requirements for Altera Devices Data Sheet*.
- (2) Minimum DC input is  $-0.5\text{ V}$ . During transitions, the inputs may undershoot to  $-2.0\text{ V}$  or overshoot to  $5.75\text{ V}$  for input currents less than  $100\text{ mA}$  and periods shorter than  $20\text{ ns}$ .
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4) Maximum  $V_{CC}$  rise time is  $100\text{ ms}$ , and  $V_{CC}$  must rise monotonically.
- (5) Minimum DC input is  $-0.5\text{ V}$ . During transitions, the inputs may undershoot to  $-2.0\text{ V}$  or overshoot to the voltage shown in the following table based on input duty cycle for input currents less than  $100\text{ mA}$ . The overshoot is dependent upon duty cycle of the signal. The DC case is equivalent to  $100\%$  duty cycle.

$V_{IN}$	Max. Duty Cycle
$4.0\text{ V}$	$100\%$ (DC)
$4.1$	$90\%$
$4.2$	$50\%$
$4.3$	$30\%$
$4.4$	$17\%$
$4.5$	$10\%$
- (6) All pins, including dedicated inputs, clock, I/O, and JTAG pins, may be driven before  $V_{CCINT}$  and  $V_{CCIO}$  are powered.
- (7) Typical values are for  $T_A = 25^\circ\text{ C}$ ,  $V_{CCINT} = 1.8\text{ V}$ , and  $V_{CCIO} = 1.8\text{ V}$ ,  $2.5\text{ V}$  or  $3.3\text{ V}$ .
- (8) These values are specified under the APEX 20KE device recommended operating conditions, shown in Table 24 on page 60.
- (9) Refer to *Application Note 117 (Using Selectable I/O Standards in Altera Devices)* for the  $V_{IH}$ ,  $V_{IL}$ ,  $V_{OH}$ ,  $V_{OL}$ , and  $I_I$  parameters when  $V_{CCIO} = 1.8\text{ V}$ .
- (10) The APEX 20KE input buffers are compatible with  $1.8\text{-V}$ ,  $2.5\text{-V}$  and  $3.3\text{-V}$  (LVTTTL and LVCMOS) signals. Additionally, the input buffers are  $3.3\text{-V}$  PCI compliant. Input buffers also meet specifications for GTL+, CTT, AGP, SSTL-2, SSTL-3, and HSTL.
- (11) The  $I_{OH}$  parameter refers to high-level TTL, PCI, or CMOS output current.
- (12) The  $I_{OL}$  parameter refers to low-level TTL, PCI, or CMOS output current. This parameter applies to open-drain pins as well as output pins.
- (13) This value is specified for normal device operation. The value may vary during power-up.
- (14) Pin pull-up resistance values will be lower if an external source drives the pin higher than  $V_{CCIO}$ .
- (15) Capacitance is sample-tested only.

Figure 33 shows the relationship between  $V_{CCIO}$  and  $V_{CCINT}$  for  $3.3\text{-V}$  PCI compliance on APEX 20K devices.

**Table 36. APEX 20KE Routing Timing Microparameters** *Note (1)*

Symbol	Parameter
$t_{F1-4}$	Fanout delay using Local Interconnect
$t_{F5-20}$	Fanout delay estimate using MegaLab Interconnect
$t_{F20+}$	Fanout delay estimate using FastTrack Interconnect

*Note to Table 36:*

- (1) These parameters are worst-case values for typical applications. Post-compilation timing simulation and timing analysis are required to determine actual worst-case performance.

**Table 37. APEX 20KE Functional Timing Microparameters**

Symbol	Parameter
TCH	Minimum clock high time from clock pin
TCL	Minimum clock low time from clock pin
TCLRP	LE clear Pulse Width
TPREP	LE preset pulse width
TESBCH	Clock high time for ESB
TESBCL	Clock low time for ESB
TESBWP	Write pulse width
TESBRP	Read pulse width

Tables 38 and 39 describe the APEX 20KE external timing parameters.

**Table 38. APEX 20KE External Timing Parameters** *Note (1)*

Symbol	Clock Parameter	Conditions
$t_{INSU}$	Setup time with global clock at IOE input register	
$t_{INH}$	Hold time with global clock at IOE input register	
$t_{OUTCO}$	Clock-to-output delay with global clock at IOE output register	C1 = 10 pF
$t_{INSUPLL}$	Setup time with PLL clock at IOE input register	
$t_{INHPLL}$	Hold time with PLL clock at IOE input register	
$t_{OUTCOPLL}$	Clock-to-output delay with PLL clock at IOE output register	C1 = 10 pF

**Table 46. EP20K200 External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSUBIDIR}}$ (1)	1.9		2.3		2.6		ns
$t_{\text{INHBIDIR}}$ (1)	0.0		0.0		0.0		ns
$t_{\text{OUTCOBIDIR}}$ (1)	2.0	4.6	2.0	5.6	2.0	6.8	ns
$t_{\text{XZBIDIR}}$ (1)		5.0		5.9		6.9	ns
$t_{\text{ZXBIDIR}}$ (1)		5.0		5.9		6.9	ns
$t_{\text{INSUBIDIR}}$ (2)	1.1		1.2		—		ns
$t_{\text{INHBIDIR}}$ (2)	0.0		0.0		—		ns
$t_{\text{OUTCOBIDIR}}$ (2)	0.5	2.7	0.5	3.1	—	—	ns
$t_{\text{XZBIDIR}}$ (2)		4.3		5.0		—	ns
$t_{\text{ZXBIDIR}}$ (2)		4.3		5.0		—	ns

**Table 47. EP20K400 External Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSU}}$ (1)	1.4		1.8		2.0		ns
$t_{\text{INH}}$ (1)	0.0		0.0		0.0		ns
$t_{\text{OUTCO}}$ (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns
$t_{\text{INSU}}$ (2)	0.4		1.0		—		ns
$t_{\text{INH}}$ (2)	0.0		0.0		—		ns
$t_{\text{OUTCO}}$ (2)	0.5	3.1	0.5	4.1	—	—	ns

**Table 48. EP20K400 External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSUBIDIR}}$ (1)	1.4		1.8		2.0		ns
$t_{\text{INHBIDIR}}$ (1)	0.0		0.0		0.0		ns
$t_{\text{OUTCOBIDIR}}$ (1)	2.0	4.9	2.0	6.1	2.0	7.0	ns
$t_{\text{XZBIDIR}}$ (1)		7.3		8.9		10.3	ns
$t_{\text{ZXBIDIR}}$ (1)		7.3		8.9		10.3	ns
$t_{\text{INSUBIDIR}}$ (2)	0.5		1.0		—		ns
$t_{\text{INHBIDIR}}$ (2)	0.0		0.0		—		ns
$t_{\text{OUTCOBIDIR}}$ (2)	0.5	3.1	0.5	4.1	—	—	ns
$t_{\text{XZBIDIR}}$ (2)		6.2		7.6		—	ns
$t_{\text{ZXBIDIR}}$ (2)		6.2		7.6		—	ns

Notes to **Tables 43 through 48**:

- (1) This parameter is measured without using ClockLock or ClockBoost circuits.
- (2) This parameter is measured using ClockLock or ClockBoost circuits.

**Tables 49 through 54** describe  $f_{MAX}$  LE Timing Microparameters,  $f_{MAX}$  ESB Timing Microparameters,  $f_{MAX}$  Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K30E APEX 20KE devices.

<b>Table 49. EP20K30E <math>f_{MAX}</math> LE Timing Microparameters</b>							
<b>Symbol</b>	<b>-1</b>		<b>-2</b>		<b>-3</b>		<b>Unit</b>
	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	
$t_{SU}$	0.01		0.02		0.02		ns
$t_H$	0.11		0.16		0.23		ns
$t_{CO}$		0.32		0.45		0.67	ns
$t_{LUT}$		0.85		1.20		1.77	ns



**Table 57. EP20K60E  $t_{MAX}$  Routing Delays**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
$t_{F1-4}$		0.24		0.26		0.30	ns
$t_{F5-20}$		1.45		1.58		1.79	ns
$t_{F20+}$		1.96		2.14		2.45	ns

**Table 58. EP20K60E Minimum Pulse Width Timing Parameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
$t_{CH}$	2.00		2.50		2.75		ns
$t_{CL}$	2.00		2.50		2.75		ns
$t_{CLRP}$	0.20		0.28		0.41		ns
$t_{PREP}$	0.20		0.28		0.41		ns
$t_{ESBCH}$	2.00		2.50		2.75		ns
$t_{ESBCL}$	2.00		2.50		2.75		ns
$t_{ESBWP}$	1.29		1.80		2.66		ns
$t_{ESBRP}$	1.04		1.45		2.14		ns

**Table 59. EP20K60E External Timing Parameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
$t_{INSU}$	2.03		2.12		2.23		ns
$t_{INH}$	0.00		0.00		0.00		ns
$t_{OUTCO}$	2.00	4.84	2.00	5.31	2.00	5.81	ns
$t_{INSUPLL}$	1.12		1.15		-		ns
$t_{INHPLL}$	0.00		0.00		-		ns
$t_{OUTCOPLL}$	0.50	3.37	0.50	3.69	-	-	ns

**Table 74. EP20K200E  $t_{MAX}$  ESB Timing Microparameters**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
$t_{ESBARC}$		1.68		2.06		2.24	ns
$t_{ESBSRC}$		2.27		2.77		3.18	ns
$t_{ESBAWC}$		3.10		3.86		4.50	ns
$t_{ESBSWC}$		2.90		3.67		4.21	ns
$t_{ESBWASU}$	0.55		0.67		0.74		ns
$t_{ESBWAH}$	0.36		0.46		0.48		ns
$t_{ESBWDSU}$	0.69		0.83		0.95		ns
$t_{ESBWDH}$	0.36		0.46		0.48		ns
$t_{ESBRASU}$	1.61		1.90		2.09		ns
$t_{ESBRAH}$	0.00		0.00		0.01		ns
$t_{ESBWESU}$	1.42		1.71		2.01		ns
$t_{ESBWEH}$	0.00		0.00		0.00		ns
$t_{ESBDATASU}$	-0.06		-0.07		0.05		ns
$t_{ESBDATAH}$	0.13		0.13		0.13		ns
$t_{ESBWADDRSU}$	0.11		0.13		0.31		ns
$t_{ESBRADDRSU}$	0.18		0.23		0.39		ns
$t_{ESBDATAO1}$		1.09		1.35		1.51	ns
$t_{ESBDATAO2}$		2.19		2.75		3.22	ns
$t_{ESBDD}$		2.75		3.41		4.03	ns
$t_{PD}$		1.58		1.97		2.33	ns
$t_{PTERMSU}$	1.00		1.22		1.51		ns
$t_{PTERMCO}$		1.10		1.37		1.09	ns

**Table 75. EP20K200E  $t_{MAX}$  Routing Delays**

Symbol	-1		-2		-3		Unit
	Min	Max	Min	Max	Min	Max	
$t_{F1-4}$		0.25		0.27		0.29	ns
$t_{F5-20}$		1.02		1.20		1.41	ns
$t_{F20+}$		1.99		2.23		2.53	ns

**Table 87. EP20K400E  $t_{MAX}$  Routing Delays**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{F1-4}$		0.25		0.25		0.26	ns
$t_{F5-20}$		1.01		1.12		1.25	ns
$t_{F20+}$		3.71		3.92		4.17	ns

**Table 88. EP20K400E Minimum Pulse Width Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{CH}$	1.36		2.22		2.35		ns
$t_{CL}$	1.36		2.26		2.35		ns
$t_{CLRP}$	0.18		0.18		0.19		ns
$t_{PREP}$	0.18		0.18		0.19		ns
$t_{ESBCH}$	1.36		2.26		2.35		ns
$t_{ESBCL}$	1.36		2.26		2.35		ns
$t_{ESBWP}$	1.17		1.38		1.56		ns
$t_{ESBRP}$	0.94		1.09		1.25		ns

**Table 89. EP20K400E External Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{INSU}$	2.51		2.64		2.77		ns
$t_{INH}$	0.00		0.00		0.00		ns
$t_{OUTCO}$	2.00	5.25	2.00	5.79	2.00	6.32	ns
$t_{INSUPLL}$	3.221		3.38		-		ns
$t_{INHPLL}$	0.00		0.00		-		ns
$t_{OUTCOPLL}$	0.50	2.25	0.50	2.45	-	-	ns

**Table 90. EP20K400E External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSUBIDIR}}$	2.93		3.23		3.44		ns
$t_{\text{INHBIDIR}}$	0.00		0.00		0.00		ns
$t_{\text{OUTCOBIDIR}}$	2.00	5.25	2.00	5.79	2.00	6.32	ns
$t_{\text{XZBIDIR}}$		5.95		6.77		7.12	ns
$t_{\text{ZXBIDIR}}$		5.95		6.77		7.12	ns
$t_{\text{INSUBIDIRPLL}}$	4.31		4.76		-		ns
$t_{\text{INHBIDIRPLL}}$	0.00		0.00		-		ns
$t_{\text{OUTCOBIDIRPLL}}$	0.50	2.25	0.50	2.45	-	-	ns
$t_{\text{XZBIDIRPLL}}$		2.94		3.43		-	ns
$t_{\text{ZXBIDIRPLL}}$		2.94		3.43		-	ns

Tables 91 through 96 describe  $f_{\text{MAX}}$  LE Timing Microparameters,  $f_{\text{MAX}}$  ESB Timing Microparameters,  $f_{\text{MAX}}$  Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K600E APEX 20KE devices.

**Table 91. EP20K600E  $f_{\text{MAX}}$  LE Timing Microparameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{SU}}$	0.16		0.16		0.17		ns
$t_{\text{H}}$	0.29		0.33		0.37		ns
$t_{\text{CO}}$		0.65		0.38		0.49	ns
$t_{\text{LUT}}$		0.70		1.00		1.30	ns

**Table 102. EP20K1000E External Bidirectional Timing Parameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{INSUBIDIR}}$	3.22		3.33		3.51		ns
$t_{\text{INHBIDIR}}$	0.00		0.00		0.00		ns
$t_{\text{OUTCOBIDIR}}$	2.00	5.75	2.00	6.33	2.00	6.90	ns
$t_{\text{XZBIDIR}}$		6.31		7.09		7.76	ns
$t_{\text{ZXBIDIR}}$		6.31		7.09		7.76	ns
$t_{\text{INSUBIDIRPLL}}$	3.25		3.26				ns
$t_{\text{INHBIDIRPLL}}$	0.00		0.00				ns
$t_{\text{OUTCOBIDIRPLL}}$	0.50	2.25	0.50	2.99			ns
$t_{\text{XZBIDIRPLL}}$		2.81		3.80			ns
$t_{\text{ZXBIDIRPLL}}$		2.81		3.80			ns

Tables 103 through 108 describe  $f_{\text{MAX}}$  LE Timing Microparameters,  $f_{\text{MAX}}$  ESB Timing Microparameters,  $f_{\text{MAX}}$  Routing Delays, Minimum Pulse Width Timing Parameters, External Timing Parameters, and External Bidirectional Timing Parameters for EP20K1500E APEX 20KE devices.

**Table 103. EP20K1500E  $f_{\text{MAX}}$  LE Timing Microparameters**

Symbol	-1 Speed Grade		-2 Speed Grade		-3 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	
$t_{\text{SU}}$	0.25		0.25		0.25		ns
$t_{\text{H}}$	0.25		0.25		0.25		ns
$t_{\text{CO}}$		0.28		0.32		0.33	ns
$t_{\text{LUT}}$		0.80		0.95		1.13	ns